

4300, Water Washable Solder Paste

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Product Data Sheet

Product Highlights

- n RELO flux classification in a Water Washable Solder Paste
- n Tier I Military/Avionic OEM approved
- n Exceptional print definition at high printing speeds up to 100mm/sec
- n Residue can be left on the board in most assemblies (not recommended for high impedance assemblies)
- n Clear Residue
- n Low voiding, including LGA components
- n Low mid-chip beading
- n REACH compliant
- n Compatible with enclosed print heads
- n Print and dispense grade solder paste available

Available Alloys

Alloy	Temp °C	Temp °F
63Sn/37Pb	183	361

Packaging

- 500 gram jars
- 700 gram cartridges
- 35 gram syringes

Test Results

Test J-STD-004 or other requirements (as stated)	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (no-clean)
Surface Insulation Resistance 85 °C, 85% RH@ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100 MΩ (no-clean)
Tack Value	IPC-TM-650: 2.4.44	37g
Viscosity - Malcom @ 10 RPM/25 °C (x10 ³ mPa/s)- Sn63/Pb37 T3/T4	IPC-TM-650: 2.4.34.4	Print: 200-275 Dispensing: 100-140
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

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Printer Operation

The following are general guidelines for stencil printer optimization with 4300. Some adjustments may be necessary based on your process requirements.

Print Speed: 25-100 mm/sec

Squeegee Pressure: 70-250g/cm of blade

Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

> 8 hours @ 30-45% RH and 20-25 °C

~ 4 hours @ 45-75% RH and 20-25 °C

Recommended Profile

This profile is designed to serve as a starting point for process optimization using 4300. To achieve better results with voiding or to reduce tombstoning, consider using a longer soaking zone, (140-180 °C) for 60-90 seconds, with a rapid pre-heat stage. If there is evidence of solder de-wetting, consider lowering the peak reflow temperature, or reduce the time above liquidus to <60 seconds.

Amtech Low Oxide Powder Distribution

Micron Size	Type	Pitch Requirements
45-75µ	Type-2	24 mil and above
25-45µ	Type-3	16-24 mil
20-38µ	Type-4	12-16 mil
15-25µ	Type-5	8-12 mil
5-15µ	Type-6	5-8 mil
2-11µ	Type-7	< 5 mil

Note: Type-6 and Type-7 may not be available in certain alloys. Other powder distributions are available on request.

Storage

Solder paste should be stored between 3-8 °C (37-46 °F) to obtain the maximum refrigerated shelf life of six months. Unopened solder paste stored at room temperature, 25 °C (77 °F) will have a one-month shelf life. Syringes and cartridges should be stored vertically in the refrigerator with the dispensing tip down. Allow 4-8 hours for solder

paste to reach an operating temperature of 20-25 °C (68-77 °F). Keep the solder paste container sealed while warming the solder paste to operating temperature. **NEVER FREEZE SOLDER PASTE.**

